## 6 Bit Digital Step Attenuator

## General Description

This document describes the specification for the IDT F1912 Digital Step Attenuator. The F1912 is part of a family of Glitch-Free ${ }^{\text {TM }}$ DSAs optimized for the demanding requirements of Base Station (BTS) radio cards and numerous other non-BTS applications.
These devices are offered in a compact $4 \mathrm{~mm} \times 4 \mathrm{~mm}$ 20 pin QFN package with $50 \Omega$ impedances for ease of integration.

## COMPETITIVE ADVANTAGE

Digital step attenuators are used in Receivers and Transmitters to provide gain control. The F1912 is a 6 -bit step attenuator optimized for these demanding applications. The silicon design has very low insertion loss and low distortion (> +60 dBm IIP3.) The device has pinpoint accuracy. Most importantly, the F1912 includes IDT's Glitch-Free ${ }^{T M}$ technology which results in low overshoot \& ringing during MSB transitions.
$\checkmark$ Glitch-Free ${ }^{T M}$ Technology so PA or ADC will not be damaged during when transitions.
$\checkmark$ Extremely accurate with low distortion.
$\checkmark$ Lowest insertion loss for best SNR

## APPLICATIONS

- Base Station 2G, 3G, 4G, TDD radio cards
- Repeaters and E911 systems
- Digital Pre-Distortion
- Point to Point Infrastructure
- Public Safety Infrastructure
- WIMAX Receivers and Transmitters
- Military Systems, JTRS radios
- RFID handheld and portable readers
- Cable Infrastructure


## Ordering Information



1 MHz to 4000 MHz

## Features

- Serial \& 6 bit Parallel Interface
- 31.5 dB Control Range
- 0.5 dB step
- Glitch-Free ${ }^{T M}$, low transient overshoot
- 3.0 V to 5.25 V supply
- 1.8 V or 3.3 V control logic
- Attenuation Error $<0.22 \mathrm{~dB}$ @ 2 GHz
- Low Insertion Loss $<1.6 \mathrm{~dB}$ @ 2 GHz
- Ultra linear IIP3 >+59.5 dBm
- IIP2 $=+110 \mathrm{dBm}$ typical
- Stable Integral Non-Linearity over temperature
- Low Current Consumption $550 \mu \mathrm{~A}$ typical
- $-40{ }^{\circ} \mathrm{C}$ to $+105^{\circ} \mathrm{C}$ operating temperature
- $4 \mathrm{~mm} \times 4 \mathrm{~mm}$ Thin QFN 20 pin package

FUNCTIONAL BLOCK DIAGRAM


## Part\# Details

| Part\# | Freq Range <br> $(\mathrm{MHz})$ | Resolution / <br> Range (dB) | Control | IL <br> (dB) | Pinout |
| :---: | :---: | :---: | :---: | :---: | :---: |
| F1950 | $150-4000$ | $0.25 / 31.75$ |  <br> Serial | 1.3 | PE43702 <br> PE43701 |
| F1951 | $100-4000$ | $0.50 / 31.5$ | Serial Only | 1.2 | HMC305 |
| F1952 | $100-4000$ | $0.50 / 15.5$ | Serial Only | 0.9 | HMC305 |
| F1953 | $400-4000$ | $0.50 / 31.5$ |  <br> Serial | 1.3 | PE4302 <br> DAT-31R5 |
| F1956 | $1-4000$ | $0.25 / 31.75$ |  <br> Serial | 1.4 | PE43705, <br> RFSA3715 |
| F1912 | $\mathbf{1 - 4 0 0 0}$ | $\mathbf{0 . 5 0 / 3 1 . 5}$ |  <br> Serial | $\mathbf{1 . 4}$ | PE4312 <br> PE4302 |

## 6 Bit Digital Step Attenuator

## Absolute Maximum Ratings

| Parameter | Symbol | Min | Max | Units |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{DD}}$ to GND | VDD | -0.3 | +5.5 | V |
| DATA, LE, CLK, D[5:0] | V Logic | -0.3 | $\begin{gathered} \operatorname{Min}\left(V_{\mathrm{DD}}-0.3,\right. \\ 3.6) \end{gathered}$ | V |
| RF1, RF2 | $\mathrm{V}_{\text {RF }}$ | -0.3 | +0.3 | V |
| Maximum Input Power applied to RF1 or RF2 (>100 MHz) | Prf |  | +34 | dBm |
| Operating Case Temperature |  |  | +105 | ${ }^{\circ} \mathrm{C}$ |
| Maximum Junction Temperature | $\mathrm{T}_{\text {max }}$ |  | +140 | ${ }^{\circ} \mathrm{C}$ |
| Junction Temperature | $\mathrm{T}_{\text {jmax }}$ |  | 140 | ${ }^{\circ} \mathrm{C}$ |
| Continuous Power Dissipation |  |  | 1.5 | W |
| Storage Temperature Range | $\mathrm{T}_{\text {st }}$ | -65 | 150 | ${ }^{\circ} \mathrm{C}$ |
| Lead Temperature (soldering, 10s) |  |  | 260 | ${ }^{\circ} \mathrm{C}$ |
| Electrostatic Discharge - HBM (JEDEC/ESDA JS-001-2012) | VESDHBM |  | $\begin{gathered} 2000 \\ \text { (Class 2) } \end{gathered}$ | Volts |
| ESD Voltage - CDM (Per JESD22-C101F) | Vesdcdm |  | $\begin{gathered} 500 \\ \text { (Class C2) } \\ \hline \end{gathered}$ | Volts |

Stresses above those listed above may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ESD Caution

This product features proprietary protection circuitry. However, it may be damaged if subjected to high energy ESD. Please use proper ESD precautions when handling to avoid damage or loss of performance.

## Package Thermal and Moisture Characteristics

$\theta_{\mathrm{JA}}$ (Junction - Ambient)
$\theta_{\mathrm{cc}}$ (Junction - Case) [The Case is defined as the exposed paddle]
Moisture Sensitivity Rating (Per J-STD-020)
$50^{\circ} \mathrm{C} / \mathrm{W}$
$3^{\circ} \mathrm{C} / \mathrm{W}$
MSL1

## 6 Bit Digital Step Attenuator

## F1912 Recommended Operating Conditions

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
| :--- | :---: | :--- | :---: | :---: | :---: | :---: |
| Supply Voltage(s) | $\mathrm{V}_{\mathrm{DD}}$ |  | 3 |  | 5.25 | V |
| Frequency Range | $\mathrm{F}_{\mathrm{RF}}$ |  | 1 |  | 4000 | MHz |
| Operating Temperature Range | TCASE | Exposed Paddle | -40 |  | 105 | ${ }^{\circ} \mathrm{C}$ |
| RF CW Input Power | PCW | RF1 or RF2 |  |  | See <br> Figure 1 | dBm |
| Source Impedance | Z Source | Single Ended |  | 50 |  | $\Omega$ |
| Load Impedance | ZLoad | Single Ended |  | 50 |  | $\Omega$ |



Figure 1 Maximum Continuous Operating RF input power versus Input Frequency

## 6 Bit Digital Step Attenuator <br> F1912 Specification

1 MHz to 4000 MHz

Specifications apply at $\mathrm{V}_{\mathrm{DD}}=+3.3 \mathrm{~V}$, $\mathrm{T}_{\text {CASE }}=+25^{\circ} \mathrm{C}$, $\mathrm{F}_{\mathrm{RF}}=2000 \mathrm{MHz}$, $\mathrm{P}_{\text {in }}=0 \mathrm{dBm}$, Serial Mode $\left(\mathrm{V}_{\text {mode }}>\mathrm{V}_{\mathrm{IH}}\right)$, $Z_{\text {source }}=Z_{\text {Load }}=50 \Omega$ unless otherwise noted. EvKit losses are de-embedded.

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Logic Input High | $\mathrm{V}_{\mathrm{IH}}$ | All Control Pins |  |  |  |  |
|  |  | $\mathrm{V}_{\mathrm{DD}}>3.9 \mathrm{~V}$ | 1.17 |  | 3.6 | V |
|  |  | $3.0 \leq \mathrm{V}_{\mathrm{DD}} \leq 3.9 \mathrm{~V}$ | 1.17 |  | $\mathrm{V}_{\mathrm{DD}} 0.3$ | V |
| Logic Input Low | VIL | All Control Pins |  |  | 0.63 | V |
| Logic Current | IIf, IIL | All Control Pins | -35 |  | +35 | $\mu \mathrm{A}$ |
| Supply Current | IDD | $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}$ |  | 550 | $830{ }^{1}$ | $\mu \mathrm{A}$ |
|  |  | $\mathrm{V}_{\mathrm{DD}}=5.0 \mathrm{~V}$ |  | 620 | 900 |  |
| RF1 Return Loss | $\mathrm{S}_{11}$ |  |  | 18 |  | dB |
| RF2 Return Loss | $\mathrm{S}_{22}$ |  |  | 18 |  | dB |
| Attenuation Step | LSB | Least Significant Bit |  | 0.5 |  | dB |
| Insertion Loss (Minimum Attenuation) | Amin | D[5:0]=[000000] (IL State) |  | 1.4 | 2.0 | dB |
| Insertion Loss (Maximum Attenuation) | Amax | $\mathrm{D}[5: 0]=[111111]=31.5 \mathrm{~dB}$ | $32^{2}$ | 33.0 |  | dB |
| Step Error | DNL |  |  | 0.10 |  | dB |
| Absolute Error | INL | $\mathrm{D}[5: 0]=[100111]=19.5 \mathrm{~dB}$ | -0.7 |  | +0.5 | dB |
| Insertion Phase Delta | $\Phi_{\Delta}$ | At 2 GHz |  | 27 |  | degrees |
|  |  | At 4 GHz |  | 55 |  |  |
| Input IP3 | IIP3 | PIN $=+10 \mathrm{dBm} /$ tone, Tone Spacing $=50 \mathrm{MHz}$ |  |  |  |  |
|  |  | Attn $=0.0 \mathrm{~dB}, \mathrm{RF}$ in $=$ RF1 | 60 | 64.0 |  | dBm |
|  |  | Attn $=0.0 \mathrm{~dB}, \mathrm{RF}$ in $=$ RF2 | 56 | 60.5 |  |  |
|  |  | Attn $=15.5 \mathrm{~dB}, \mathrm{RF}$ in $=$ RF1 | 56 | 61.0 |  |  |
|  |  | Attn $=15.5 \mathrm{~dB}, \mathrm{RF}$ in $=\mathrm{RF} 2$ | 57 | 61.5 |  |  |
|  |  | Attn $=0.00 \mathrm{~dB}, R F_{\text {in }}=R F 1$ <br> PIN $=+22 \mathrm{dBm}$ per tone <br> 1 MHz Tone Separation |  |  |  |  |
|  |  | $\mathrm{F}_{\mathrm{RF}}=0.7 \mathrm{GHz}$ | 60 | 62.5 |  |  |
|  |  | $\mathrm{F}_{\mathrm{RF}}=1.8 \mathrm{GHz}$ | 58 | 61.5 |  |  |
|  |  | $\mathrm{F}_{\mathrm{RF}}=2.2 \mathrm{GHz}$ | 58 | 61.0 |  |  |
|  |  | $\mathrm{F}_{\mathrm{RF}}=2.6 \mathrm{GHz}$ | 57 | 60.5 |  |  |
| Input IP2 | IIP2 | $\begin{aligned} & \hline \mathrm{P}_{\mathrm{IN}}=+12 \mathrm{dBm} / \text { tone, } \mathrm{V}_{\mathrm{DD}}=5.0 \mathrm{~V} \\ & \mathrm{~F} 1=945 \mathrm{MHz}, \mathrm{F2} 2=949 \mathrm{MHz} \\ & \mathrm{~F}_{1}+\mathrm{F2} 2=1894 \mathrm{MHz} \\ & \text { RFIN }^{\mathrm{IN}}=\mathrm{RF} 1 \end{aligned}$ |  | 110 |  | dBm |
| 0.1 dB Compression ${ }^{3}$ | P0.1 | $\mathrm{D}[5: 0]=[000000]=0 \mathrm{~dB}$ |  | 31 |  | dBm |

Note 1: Items in min/max columns in bold italics are Guaranteed by Test.
Note 2: Items in $\mathrm{min} / \mathrm{max}$ columns that are not bold/italics are Guaranteed by Design Characterization.
Note 3: The input 0.1 dB compression point is a linearity figure of merit. Refer to Absolute Maximum Ratings section for the maximum RF input power.
Note 4: Spurious due to on-chip negative voltage generator. Typical generator fundamental frequency is 2.2 MHz .
Note 5: Speeds are measured after SPI programming is completed (data latched with LE = HIGH).

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## F1912 SPECIFICATION (CONTINUED)

Specifications apply at $\mathrm{V}_{\mathrm{DD}}=+3.3 \mathrm{~V}$, $\mathrm{T}_{\text {CASE }}=+25^{\circ} \mathrm{C}$, $\mathrm{F}_{\mathrm{RF}}=2000 \mathrm{MHz}$, P in $=0 \mathrm{dBm}$, Serial Mode $\left(\mathrm{V}_{\text {mode }}>\mathrm{V}_{\mathrm{IH}}\right)$, $Z_{\text {source }}=Z_{\text {Load }}=50 \Omega$ unless otherwise noted. EvKit losses are de-embedded.

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| MSB Step Time | TLsb | Start LE rising edge > $\mathrm{V}_{\mathrm{IH}}$ End $\pm 0.10 \mathrm{~dB}$ Pout settling for 15.5 dB to 16.0 dB transition |  | 500 |  | ns |
| Maximum spurious level on any RF port ${ }^{4}$ | Spurmax |  |  | -140 |  | dBm |
| Maximum Switching Frequency | SW Freq |  |  | 25 |  | kHz |
| DSA Settling time | $\tau$ ¢et | Max to Min Attenuation to settle to within 0.5 dB of final value |  | 0.9 |  | $\mu \mathrm{S}$ |
|  |  | Min to Max Attenuation to settle to within 0.5 dB of final value |  | 1.8 |  |  |
| Control Interface | SPI вit $^{\text {d }}$ |  |  | 6 |  | bit |
| Serial Clock Speed | SPİık |  |  |  | 25 | MHz |

Note 1: Items in min/max columns in bold italics are Guaranteed by Test.
Note 2: Items in min/max columns that are not bold/italics are Guaranteed by Design Characterization.
Note 3: The input 0.1 dB compression point is a linearity figure of merit. Refer to Absolute Maximum Ratings section for the maximum RF input power.
Note 4: Spurious due to on-chip negative voltage generator. Typical generator fundamental frequency is 2.2 MHz .
Note 5: Speeds are measured after SPI programming is completed (data latched with LE = HIGH).

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## Programming Options

F1912 can be programmed using either the parallel or serial interface which is selectable via Vmode (pin 13). Serial mode is selected by floating $\mathrm{V}_{\text {MODE }}$ or pulling it to a voltage logic high (greater than $\mathrm{V}_{\text {IH }}$ ) and parallel mode is selected by setting $\mathrm{V}_{\text {mode }}$ to logic low (less than $\mathrm{V}_{\text {IL }}$ ).

## Serial Control Mode

F1912 Serial mode is selected by floating $\mathrm{V}_{\text {mode }}$ (pin 13) or pulling it to a voltage $>\mathrm{V}_{\text {IH }}$. The serial interface is a 6 bit shift register to shift in the data MSB (D5) first. When serial programming is used, all the parallel control input pins ( $1,15,16,17,19,20$ ) must be grounded.

Table 1-6 Bit SPI Word Sequence

| D5 | Attenuation 16 dB Control Bit |
| :---: | :---: |
| D4 | Attenuator 8 dB Control Bit |
| D3 | Attenuator 4 dB Control Bit |
| D2 | Attenuator 2 dB Control Bit |
| D1 | Attenuator 1 dB Control Bit |
| D0 | Attenuator 0.5 dB Control Bit |

Table 2 - Truth Table for Serial Control Word

| D5 <br> (MSB) | D4 | D3 | D2 | D1 | D0 <br> (LSB) | Attenuation <br> $\mathbf{( d B )}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| 0 | 0 | 0 | 0 | 0 | 1 | 0.5 |
| 0 | 0 | 0 | 0 | 1 | 0 | 1 |
| 0 | 0 | 0 | 1 | 0 | 0 | 2 |
| 0 | 0 | 1 | 0 | 0 | 0 | 4 |
| 0 | 1 | 0 | 0 | 0 | 0 | 8 |
| 1 | 0 | 0 | 0 | 0 | 0 | 16 |
| 1 | 1 | 1 | 1 | 1 | 1 | 31.5 |

## Serial Mode Register Timing Diagram: (Note the Timing Spec Intervals in Blue)

With serial control, the F1912 can be programmed via the serial port on the rising edge of Latch Enable (LE) which loads the last 6 DATA line bits [formatted MSB (D5) first] resident in the SHIFT register followed by the next 5 bits.


Figure 2 - Serial Register Timing Diagram

Note - When Latch enable is high, the shift register is disabled and DATA is NOT continuously clocked into the shift register which minimizes noise. It is recommended that Latch enable be left high when the device is not being programmed.

Table 3 - Serial Mode Timing Table

| Interval <br> Symbol | Description | Min <br> Spec | Max <br> Spec | Units |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{mc}}$ | Parallel to Serial Setup Time - From rising edge <br> of V | $\mathbf{1 0 0}$ |  | ns |
| $\mathrm{t}_{\mathrm{ds}}$ | Clock high pulse width | $\mathbf{1 0}$ |  | ns |
| $\mathrm{t}_{\mathrm{cls}}$ | LE Setup Time - From the rising edge of CLK <br> pulse for D0 to LE rising edge minus half the <br> clock period. | $\mathbf{1 0}$ |  | ns |
| $\mathrm{t}_{\text {lew }}$ | LE pulse width | $\mathbf{3 0}$ |  | ns |
| $\mathrm{t}_{\text {dsc }}$ | Data Setup Time - From the starting edge of <br> Data bit to rising edge of CLK | $\mathbf{1 0}$ |  | ns |
| $\mathrm{T}_{\text {dht }}$ | Data Hold Time - From rising edge of CLK to <br> falling edge of the Data bit. | $\mathbf{1 0}$ |  | ns |

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## Serial Mode Default Startup Condition:

When the device is first powered up it will default to the Maximum Attenuation of 31.5 dB independent of the VMODE and parallel pin [D5:D0] conditions.

Table 4 - Default Control Word for the Serial Mode

| D5 <br> (MSB) | D4 | D3 | D2 | D1 | D0 <br> (LSB) | Attenuation <br> (dB) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 1 | 1 | 1 | 1 | 1 | 1 | 31.5 |

## Parallel Control Mode

For the F1912 the user has the option of running in one of two parallel modes. Direct Parallel Mode or Latched Parallel Mode.

## Direct Parallel Mode:

Direct Parallel Mode is selected when $\mathrm{V}_{\text {mode }}$ (pin 13) is less than $\mathrm{V}_{\text {IL }}$ and LE (pin 5 ) is greater than $\mathrm{V}_{\text {IH }}$. In this mode the device will immediately react to any voltage changes to the parallel control pins [pins $1,15,16,17$, 19, 20]. Use direct parallel mode for the fastest settling time.

## Latched Parallel Mode:

Latched Parallel Mode is selected when $\mathrm{V}_{\text {MODE }}$ is less than $\mathrm{V}_{\text {IL }}$ and LE (pin 5) is toggled from less than $\mathrm{V}_{\text {IL }}$ to greater than $\mathrm{V}_{\text {IH }}$. To utilize Latched Parallel Mode:

- Set LE < VIL
- Adjust pins [pins $1,15,16,17,19,20$ ] to the desired attenuation setting. (Note the device will not react to these pins while LE < VIL.)
- Pull $\mathrm{LE}>\mathrm{V}_{\mathrm{IH}}$. The device will then transition to the attenuation settings reflected by pins D 5 - D0. Latched Parallel Mode implies a default state for when the device is first powered up with VMODE < VII and LE < VIL. In this case the default setting is MAXIMUM Attenuation.

Table 5 - Truth Table for the Parallel Control Word

| D5 | D4 | D3 | D2 | D1 | D0 | Attenuation <br> $\mathbf{( d B )}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| 0 | 0 | 0 | 0 | 0 | 1 | 0.5 |
| 0 | 0 | 0 | 0 | 1 | 0 | 1 |
| 0 | 0 | 0 | 1 | 0 | 0 | 2 |
| 0 | 0 | 1 | 0 | 0 | 0 | 4 |
| 0 | 1 | 0 | 0 | 0 | 0 | 8 |
| 1 | 0 | 0 | 0 | 0 | 0 | 16 |
| 1 | 1 | 1 | 1 | 1 | 1 | 31.5 |



Figure 3 - Latched Parallel Mode Timing Diagram

Table 6 - Latched Parallel Mode Timing

| Interval <br> Symbol | Description | Min <br> Spec | Max <br> Spec | Units |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{tps}}$ | Serial to Parallel Mode Setup Time | 100 |  | ns |
| $\mathrm{t}_{\mathrm{pdh}}$ | Parallel Data Hold Time | 10 |  | ns |
| $\mathrm{t}_{\mathrm{pds}}$ | LE minimum pulse width | 10 |  | ns |
| $\mathrm{t}_{\mathrm{le}}$ | Parallel Data Setup Time | 10 |  | ns |

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## Typical Operating Conditions (TOC)

Unless otherwise noted for the TOC graphs on the following pages, the following conditions apply.

- $V_{D D}=+3.30 \mathrm{~V}$
- $\mathrm{T}_{\text {case }}=+25^{\circ} \mathrm{C}$
- $\mathrm{F}_{\mathrm{RF}}=\mathbf{2} \mathbf{~ G H z}$
- $P_{\text {In }}=0 \mathbf{d B m}$ for single tone measurements
- $P_{\text {in }}=\boldsymbol{+ 1 0} \mathbf{d B m} /$ tone for multi-tone measurements
- Tone Spacing $=\mathbf{5 0} \mathbf{~ M H z}$
- EVKit connector and board losses are de-embedded


## Typical Operating Conditions (- 1 -)

## Insertion Loss vs Frequency



RF1 (Input) Return Loss vs Frequency [All States]


RF2 (Output) Return Loss vs Frequency [All States]


## Insertion Loss vs Attenuation State



RF1 (Input) Return Loss vs Attenuation State


RF2 (Output) Return Loss vs Attenuation State


## Typical Operating Conditions (- 2 -)

## Relative Insertion Phase vs Frequency



Worst Case Absolute Accuracy vs Frequency


Worst Case Step Accuracy vs Frequency


Relative Insertion Phase vs Attenuation


## Absolute Accuracy vs Attenuation



Step Accuracy vs Attenuation


## 6 Bit Digital Step Attenuator

## Typical Operating Conditions (- 3 -)

## Compression at 0 dB and 2 GHz



Compression at $\mathbf{1 5 . 5} \mathbf{~ d B}$ and $2 \mathbf{~ G H z}$


Compression at $\mathbf{3 1 . 5} \mathbf{~ d B}$ and $2 \mathbf{~ G H z}$


Input IP3 - 0 dB, +22 dBm, 1 MHz Tone Delta, RF1


Input IP3 (Low Side) vs attenuation at $\mathbf{2 G H z}$


Input IP3 (High Side) vs attenuation at 2GHz


## IDTF1912NCGI Datasheet

## Package Drawing

(4 mm x 4 mm 20-pin TQFN), NCG20


## Land Pattern Dimension



TOP View
(looking through the top of the package)


* Device is RF Bi-Directional


## Pin Description

| PIN | NAME | FUNCTION |
| :---: | :---: | :---: |
| 1 | D5 | 16 dB Attenuation Control Bit. Pull high for 16 dB ATTN. |
| 2 | RF1 | Device RF input or output (bi-directional). Internally DC blocked. |
| 3 | DATA | Serial interface Data Input. |
| 4 | CLK | Serial interface Clock Input. |
| 5 | LE | Serial interface Latch Enable Input. Internal pullup (100K ohm). |
| 6 | VDD | Power supply pin. |
| 7 | NC | Internally unconnected. |
| 8 | NC | Internally unconnected. |
| 9 | NC | Internally unconnected. |
| 10 | GND | Connect to Ground. This pin is internally connected to the exposed paddle. |
| 11 | GND | Connect to Ground. This pin is internally connected to the exposed paddle. |
| 12 | GND | Connect to Ground. This pin is internally unconnected. |
| 13 | VMODE | Pull high for serial control mode. Ground for parallel control mode. |
| 14 | RF2 | Device RF input or output (bi-directional). Internally DC blocked. |
| 15 | D4 | 8 dB Attenuation Control Bit. Pull high for 8 dB ATTN. |
| 16 | D3 | 4 dB Attenuation Control Bit. Pull high for 4 dB ATTN. |
| 17 | D2 | 2 dB Attenuation Control Bit. Pull high for 2 dB ATTN. |
| 18 | GND | Connect to Ground. This pin is internally unconnected. |
| 19 | D1 | 1 dB Attenuation Control Bit. Pull high for 1 dB ATTN. |
| 20 | D0 | 0.5 dB Attenuation Control Bit. Pull high for 0.5 dB ATTN. |
| EP | Exposed Paddle | Exposed Pad. Internally connected to GND. Solder this exposed pad to a PCB pad that uses multiple ground vias to provide heat transfer out of the device into the PCB ground planes. These multiple via grounds are also required to achieve the specified RF performance. |

IDTF1912NCGI
Datasheet

6 Bit Digital Step Attenuator
1 MHz to 4000 MHz

## EvKit Picture



## EVkit / Applications Circuit



| Item \# | Part Reference | QTY | DESCRIPTION | Mfr. Part \# | Mfr. |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1 | C1, C11 | 2 | $100 \mathrm{nF} \pm 10 \%, 50 \mathrm{~V}, \mathrm{X} 7 \mathrm{R}$ Ceramic Capacitor <br> (0402) | GRM155R71H104K | MURATA |
| 2 | C2, C12 | 2 | $10 \mathrm{nF} \pm 5 \%, 50 \mathrm{~V}$, C0G Ceramic Capacitor (0402) | GRM155R71H103J | MURATA |
| 3 | R12, C13, C14 | 3 | $0 \Omega$ Resistors (0402) | ERJ-2GEOR00X | PANASONIC |
| 4 | R1-R7 | 7 | $100 \Omega \pm 1 \%, 1 / 10 \mathrm{~W}$, Resistor (0402) | ERJ-2RKF1000X | PANASONIC |
| 5 | R9, R10, R11 | 3 | $3 \mathrm{k} \Omega \pm 1 \%, 1 / 10 \mathrm{~W}$, Resistor (0402) | ERJ-2RKF3001X | PANASONIC |
| 6 | R8, R15, R16, R17 | 4 | 10k $\Omega \pm 1 \%, 1 / 10 \mathrm{~W}$, Resistor (0402) | ERJ-2RKF1002X | PANASONIC |
| 7 | R13 | 1 | $100 \mathrm{~K} \Omega \pm 1 \%, 1 / 10 \mathrm{~W}$, Resistor (0402) | ERJ-2RKF1003X | PANASONIC |
| 8 | R14 | 1 | 267K $2 \pm 1 \%, 1 / 10 \mathrm{~W}$, Resistor (0402) | ERJ-2RKF2673X | PANASONIC |
| 9 | J5, J7 | 2 | CONN HEADER VERT SGL $2 \times 1$ POS GOLD | 961102-6404-AR | 3M |
| 10 | J8 | 1 | CONN HEADER VERT SGL $4 \times 1$ POS GOLD | 961104-6404-AR | 3M |
| 11 | J6 | 1 | CONN HEADER VERT SGL $8 \times 1$ POS GOLD | 961108-6404-AR | 3M |
| 12 | J2, J3, 34 | 3 | Edge Launch SMA ( 0.250 inch pitch ground, round) | 142-0711-821 | Emerson Johnson |
| 13 | U1 | 1 | SWITCH 8 POSITION DIP SWITCH | KAT1108E | E-Switch |
| 14 | U2 | 1 | DSA | F1912Z | IDT |
| 15 |  | 1 | Printed Circuit Board (Rev 01) | F1953S Evkit Rev 01 | IDT |
| 16 |  |  | Bill Of Material (Rev 01) |  |  |

## Top Markings



## Applications Information

F1912 Digital Pin Voltage \& Resistance Values (pins not connected)
The following table lists the resistance between various pins and ground when no DC power is applied. When the device is powered up with +5 Volts DC these same pins to should have the measured voltage to ground.

| Pin | Name | DC voltage <br> (volts) | Resistance <br> (ohms) |
| :---: | :---: | :---: | :---: |
| 13 | $V_{\text {MODE }}$ | 2.5 V | $100 \mathrm{k} \Omega$ pullup resistor <br> to internally regulated <br> 2.5 V |
| $3,4,5$ | DATA, CLK, LE | 2.5 V | $10 \mathrm{k} \Omega$ pullup resistor <br> to internally regulated <br> 2.5 V |

## Revision History

| Revision | Revision Date | Description of Change |  |
| :---: | :---: | :--- | :---: |
| 1 | $2017-M a y-26$ | Corrected pin label on Page 16. |  |
| O | 2015-June-06 | Initial release of the datasheet |  |


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